



Product Change Notification - KSRA-16BWET454

Date:

15 Aug 2019

Product Category:

Others; 16-Bit - Microcontrollers and Digital Signal Controllers; 32-bit Microcontrollers; Capacitive Touch Sensors

Affected CPNs:**Notification subject:**

CCB 3027 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products of the 0.18um TSMC wafer technology available in 44L QFN (8x8x0.9mm) package at NSEB assembly site.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18um TSMC wafer technology available in 44L QFN (8x8x0.9mm) package at NSEB assembly site.

Pre Change:

Using gold (Au) bond wire

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	UTAC Thai Limited LTD. (NSEB)	UTAC Thai Limited LTD. (NSEB)
Wire material	Au	CuPdAu
Die attach material	8600	8600
Molding compound material	G700LTD	G700LTD
Lead frame material	C194	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:



In Progress

Estimated First Ship Date:

September 15, 2019 (date code: 1938)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	July 2017						->	August 2019					September 2019				
	26	27	28	29	30	31		31	32	33	34	35	36	37	38	39	40
Initial PCN Issue Date				X													
Qual Report Availability									X								
Final PCN Issue Date									X								
Estimated Implementation Date													X				

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report

Revision History:

July 18, 2017: Issued initial notification.

August 15, 2019: Issued final notification. Attached the qualification report. Updated the affected CPN list based on the scope. Provide estimated first ship date to be on September 15, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-16BWET454_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

DSPIC33EP128GM304-E/ML
DSPIC33EP128GM304-I/ML
DSPIC33EP128GM604-E/ML
DSPIC33EP128GM604-I/ML
DSPIC33EP128GP504-E/ML
DSPIC33EP128GP504-H/ML
DSPIC33EP128GP504-I/ML
DSPIC33EP128GP504-I/MLA3
DSPIC33EP128GP504T-E/ML
DSPIC33EP128GP504T-I/ML
DSPIC33EP128MC204-E/ML
DSPIC33EP128MC204-H/ML
DSPIC33EP128MC204-I/ML
DSPIC33EP128MC204-I/MLA3
DSPIC33EP128MC204T-E/ML
DSPIC33EP128MC204T-I/ML
DSPIC33EP128MC504-E/ML
DSPIC33EP128MC504-H/ML
DSPIC33EP128MC504-I/ML
DSPIC33EP128MC504-I/MLA3
DSPIC33EP128MC504T-E/ML
DSPIC33EP128MC504T-H/ML
DSPIC33EP128MC504T-I/ML
DSPIC33EP16GS504-E/ML
DSPIC33EP16GS504-I/ML
DSPIC33EP16GS504T-E/ML
DSPIC33EP16GS504T-I/ML
DSPIC33EP256GM304-E/ML
DSPIC33EP256GM304-I/ML
DSPIC33EP256GM604-E/ML
DSPIC33EP256GM604-I/ML
DSPIC33EP256GP504-E/ML
DSPIC33EP256GP504-H/ML
DSPIC33EP256GP504-I/ML
DSPIC33EP256GP504T-E/ML
DSPIC33EP256GP504T-H/ML
DSPIC33EP256GP504T-I/ML
DSPIC33EP256MC204-E/ML
DSPIC33EP256MC204-H/ML
DSPIC33EP256MC204-I/ML
DSPIC33EP256MC204T-E/ML
DSPIC33EP256MC204T-E/MLC02
DSPIC33EP256MC204T-H/ML
DSPIC33EP256MC204T-I/ML
DSPIC33EP256MC504-E/ML
DSPIC33EP256MC504-H/ML

KSRA-16BWET454 - CCB 3027 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products of the 0.18um TSMC wafer technology available in 44L QFN (8x8x0.9mm) package at NSEB assembly site.

DSPIC33EP256MC504-I/ML
DSPIC33EP256MC504T-E/ML
DSPIC33EP256MC504T-H/ML
DSPIC33EP256MC504T-I/ML
DSPIC33EP32GP504-E/ML
DSPIC33EP32GP504-H/ML
DSPIC33EP32GP504-I/ML
DSPIC33EP32GP504T-E/ML
DSPIC33EP32GP504T-H/ML
DSPIC33EP32GP504T-I/ML
DSPIC33EP32GS504-E/ML
DSPIC33EP32GS504-I/ML
DSPIC33EP32GS504-I/MLC09
DSPIC33EP32GS504-I/MLC10
DSPIC33EP32GS504T-E/ML
DSPIC33EP32GS504T-I/ML
DSPIC33EP32GS504T-I/MLC09
DSPIC33EP32GS504T-I/MLC10
DSPIC33EP32MC204-E/ML
DSPIC33EP32MC204-H/ML
DSPIC33EP32MC204-I/ML
DSPIC33EP32MC204T-E/ML
DSPIC33EP32MC204T-H/ML
DSPIC33EP32MC204T-I/ML
DSPIC33EP32MC504-E/ML
DSPIC33EP32MC504-H/ML
DSPIC33EP32MC504-I/ML
DSPIC33EP32MC504T-E/ML
DSPIC33EP32MC504T-H/ML
DSPIC33EP32MC504T-I/ML
DSPIC33EP512GM304-E/ML
DSPIC33EP512GM304-I/ML
DSPIC33EP512GM604-E/ML
DSPIC33EP512GM604-I/ML
DSPIC33EP512GP504-E/ML
DSPIC33EP512GP504-H/ML
DSPIC33EP512GP504-I/ML
DSPIC33EP512GP504T-H/ML
DSPIC33EP512GP504T-I/ML
DSPIC33EP512MC204-E/ML
DSPIC33EP512MC204-H/ML
DSPIC33EP512MC204-I/ML
DSPIC33EP512MC204T-E/ML
DSPIC33EP512MC204T-H/ML
DSPIC33EP512MC204T-I/ML
DSPIC33EP512MC504-E/ML
DSPIC33EP512MC504-H/ML
DSPIC33EP512MC504-I/ML
DSPIC33EP512MC504T-E/ML

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DSPIC33EP512MC504T-H/ML

DSPIC33EP512MC504T-I/ML

DSPIC33EP64GP504-E/ML

DSPIC33EP64GP504-H/ML

DSPIC33EP64GP504-I/ML

DSPIC33EP64GP504-I/MLA3

DSPIC33EP64GP504T-E/ML

DSPIC33EP64GP504T-H/ML

DSPIC33EP64GP504T-I/ML

DSPIC33EP64GS504-E/ML

DSPIC33EP64GS504-E/MLC06

DSPIC33EP64GS504-I/ML

DSPIC33EP64GS504-I/MLC11

DSPIC33EP64GS504-I/MLRB3

DSPIC33EP64GS504T-E/ML

DSPIC33EP64GS504T-I/ML

DSPIC33EP64GS504T-I/MLC11

DSPIC33EP64GS504T-I/MLRB3

DSPIC33EP64MC204-E/ML

DSPIC33EP64MC204-H/ML

DSPIC33EP64MC204-I/ML

DSPIC33EP64MC204T-E/ML

DSPIC33EP64MC204T-H/ML

DSPIC33EP64MC204T-I/ML

DSPIC33EP64MC504-E/ML

DSPIC33EP64MC504-H/ML

DSPIC33EP64MC504-I/ML

DSPIC33EP64MC504T-E/ML

DSPIC33EP64MC504T-H/ML

DSPIC33EP64MC504T-I/ML

DSPIC33EV128GM004-E/ML

DSPIC33EV128GM004-H/ML

DSPIC33EV128GM004-I/ML

DSPIC33EV128GM004T-I/ML

DSPIC33EV128GM104-E/ML

DSPIC33EV128GM104-H/ML

DSPIC33EV128GM104-I/ML

DSPIC33EV128GM104T-I/ML

DSPIC33EV256GM004-E/ML

DSPIC33EV256GM004-H/ML

DSPIC33EV256GM004-I/ML

DSPIC33EV256GM004T-I/ML

DSPIC33EV256GM104-E/ML

DSPIC33EV256GM104-H/ML

DSPIC33EV256GM104-I/ML

DSPIC33EV256GM104T-I/ML

DSPIC33EV64GM004-E/ML

DSPIC33EV64GM004-H/ML

DSPIC33EV64GM004-I/ML

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DSPIC33EV64GM004I-I/ML
DSPIC33EV64GM104-E/ML
DSPIC33EV64GM104-H/ML
DSPIC33EV64GM104-I/ML
DSPIC33EV64GM104T-I/ML
HA7619-I/ML027
HA7619T-I/ML025
HA7619T-I/ML027
MTCH6301-I/ML
MTCH6301T-I/ML
PIC24EP128GP204-E/ML
PIC24EP128GP204-H/ML
PIC24EP128GP204-I/ML
PIC24EP128GP204-I/MLA3
PIC24EP128GP204T-I/ML
PIC24EP128MC204-E/ML
PIC24EP128MC204-H/ML
PIC24EP128MC204-I/ML
PIC24EP128MC204-I/MLA3
PIC24EP128MC204T-I/ML
PIC24EP256GP204-E/ML
PIC24EP256GP204-H/ML
PIC24EP256GP204-I/ML
PIC24EP256GP204T-E/ML
PIC24EP256GP204T-H/ML
PIC24EP256GP204T-I/ML
PIC24EP256GP204T-I/ML029
PIC24EP256MC204-E/ML
PIC24EP256MC204-H/ML
PIC24EP256MC204-I/ML
PIC24EP256MC204T-E/ML
PIC24EP256MC204T-H/ML
PIC24EP256MC204T-I/ML
PIC24EP32GP204-E/ML
PIC24EP32GP204-H/ML
PIC24EP32GP204-I/ML
PIC24EP32GP204T-E/ML
PIC24EP32GP204T-H/ML
PIC24EP32GP204T-I/ML
PIC24EP32MC204-E/ML
PIC24EP32MC204-H/ML
PIC24EP32MC204-I/ML
PIC24EP32MC204T-E/ML
PIC24EP32MC204T-H/ML
PIC24EP32MC204T-I/ML
PIC24EP512GP204-E/ML
PIC24EP512GP204-H/ML
PIC24EP512GP204-I/ML
PIC24EP512GP204T-E/ML

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PIC24EP512GP204I-H/ML
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PIC24EP512MC204-E/ML
PIC24EP512MC204-H/ML
PIC24EP512MC204-I/ML
PIC24EP512MC204T-E/ML
PIC24EP512MC204T-H/ML
PIC24EP512MC204T-I/ML
PIC24EP64GP204-E/ML
PIC24EP64GP204-H/ML
PIC24EP64GP204-I/ML
PIC24EP64GP204-I/MLA3
PIC24EP64GP204T-E/ML
PIC24EP64GP204T-H/ML
PIC24EP64GP204T-I/ML
PIC24EP64MC204-E/ML
PIC24EP64MC204-H/ML
PIC24EP64MC204-I/ML
PIC24EP64MC204T-E/ML
PIC24EP64MC204T-H/ML
PIC24EP64MC204T-I/ML
PIC24FJ128GA204-I/ML
PIC24FJ128GA204T-I/ML
PIC24FJ128GB204-E/ML
PIC24FJ128GB204-I/ML
PIC24FJ128GB204T-I/ML
PIC24FJ64GA204-E/ML
PIC24FJ64GA204-I/ML
PIC24FJ64GA204T-I/ML
PIC24FJ64GB204-E/ML
PIC24FJ64GB204-I/ML
PIC32MX110F016D-I/ML
PIC32MX110F016DT-I/ML
PIC32MX110F016DT-V/ML
PIC32MX110F016D-V/ML
PIC32MX120F032D-50I/ML
PIC32MX120F032D-I/ML
PIC32MX120F032DT-50I/ML
PIC32MX120F032DT-I/ML
PIC32MX120F032DT-V/ML
PIC32MX120F032D-V/ML
PIC32MX130F064D-I/ML
PIC32MX130F064DT-I/ML
PIC32MX130F064DT-V/ML
PIC32MX130F064D-V/ML
PIC32MX150F128D-50I/ML
PIC32MX150F128D-I/ML
PIC32MX150F128DT-50I/ML
PIC32MX150F128DT-I/ML

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PIC32MX150F128DT-V/ML
PIC32MX150F128D-V/ML
PIC32MX170F256D-I/ML
PIC32MX170F256DT-I/ML
PIC32MX170F256DT-V/ML
PIC32MX170F256D-V/ML
PIC32MX210F016D-I/ML
PIC32MX210F016DT-I/ML
PIC32MX210F016DT-V/ML
PIC32MX210F016D-V/ML
PIC32MX220F032D-50I/ML
PIC32MX220F032D-I/ML
PIC32MX220F032DT-50I/ML
PIC32MX220F032DT-I/ML
PIC32MX220F032DT-V/ML
PIC32MX220F032D-V/ML
PIC32MX230F064D-I/ML
PIC32MX230F064DT-I/ML
PIC32MX230F064DT-V/ML
PIC32MX230F064D-V/ML
PIC32MX250F128D-50I/ML
PIC32MX250F128D-I/ML
PIC32MX250F128DT-50I/ML
PIC32MX250F128DT-I/ML
PIC32MX250F128DT-I/ML026
PIC32MX250F128DT-V/ML
PIC32MX250F128D-V/ML
PIC32MX270F256D-I/ML
PIC32MX270F256DT-I/ML
PIC32MX270F256DT-V/ML
PIC32MX270F256D-V/ML
WP200TX01-E/ML001
WP200TX01T-E/ML001